EXPEGO SPLIT AXIS MACHINE

VERSATILE LASER SYSTEM FOR MICRO MATERIAL PROCESSING
**FEATURES**
- High precise and ultrafast laser system
- Single or dual process head setup
- Integration of up to 3 laser systems
- In-situ scanner calibration
- InnoLas µVision system for high precise substrate alignment
- Operation system Windows 10 IoT
- Automatic laser to camera offset calibration

**OPTIONS**
- InnoLas Postprocessor – Import of CAD files (e.g. DXF, DWG, Gerber)
- SQL data base for process and event tracking
- MES interface (SECS,GEM,PV2, OPC,UA)
- Integrated process metrology
- Fully-automatic handling system
- INFINITY Scan to avoid stitching errors (simultaneous axis and scanner movement)

**APPLICATIONS**
- Micro Via Drilling, Routing, Depaneling, Micro Structuring, Selective Ablation, Cavity Formation

**ACCURACY**
- < +/-5 µm abs. ( +/- .0 00019 Inches)
- < +/-2 µm repeatability ( +/- .00 00078 Inches)

**SUBSTRATES**
- Dimension up to 750 mm x 750 mm (29.5 x 29.5 Inches)
- Rigid-, flex-PCBs, ceramic, glass and advanced materials

**AVAILABLE LASER SOURCES**
- Wavelength: 9.4, 10.6 µm (CO₂), 1064, 1030, 532, 515, 355 nm
- Pulse: µs, ns, ps, fs

**DIMENSIONS**
- 1750 x 2200 x 2600 mm (69 x 87 x 103 Inches)